

1 ABSTRACT OF THE DISCLOSURE

A process for preparing a semiconductor member comprises the steps of:

- forming a member having a non-porous
3 monocrystalline semiconductor region on a porous
monocrystalline semiconductor region,

- bonding the surface of a member of which the
surface is constituted of an insulating substance onto
the surface of the non-porous monocrystalline
10 semiconductor region, and then

removing the porous monocrystalline
semiconductor region by etching.

15

20

25

This Sheet Has Been Replaced

